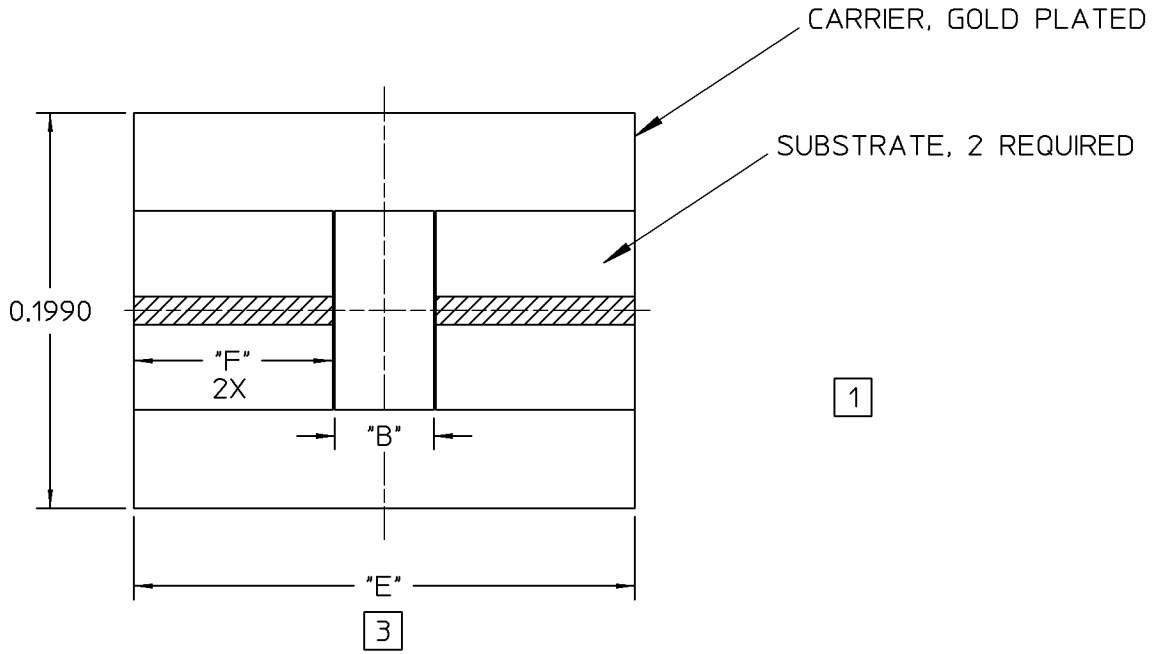
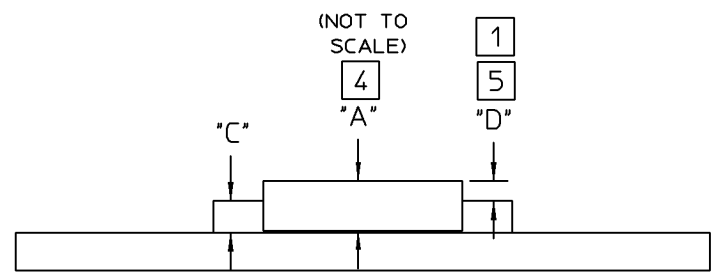
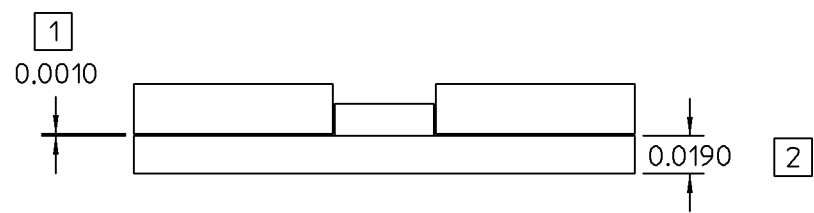


REV	ECN NO.	INIT	DATE



A = _____ = SUBSTRATE THICKNESS
 B = _____ = PEDESTAL WIDTH
 C = _____ = PEDESTAL HEIGHT = A + 0.001 - D
 D = _____ = DUT THICKNESS + DUT ATTACHMENT
 E = _____ = 2(F) + 0.006 + B 3
 F = 0.1000 = SUBSTRATE LENGTH
 G: SELECT SUBSTRATE ATTACHMENT
 SILVER EPOXY OR AuGe SOLDER



MANUFACTURING NOTES:

- 1 ALLOW 0.0010 THICKNESS FOR SUBSTRATE ATTACHMENT
- 2 0.0190 IS CARRIER THICKNESS
- 3 0.003 GAP REQUIRED BETWEEN PEDESTAL AND SUBSTRATES.
- 4 *A* DIMENSION IS SUBSTRATE THICKNESS (10, 15 OR 25 MILS)
- 5 *D* DIMENSION IS TOP OF PEDESTAL TO TOP OF SUBSTRATE

INTERCONTINENTAL MICROWAVE			
FET CARRIER ASSY DATA INPUT FORM			
SIZE	PART NO.	REV	VER.
A	B0137216		